

PCN Number:	20240329000.1			PCN Date:	March 29, 2024
Title:	Qualification of Clark as an additional Assembly site for select devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	June 27, 2024		Sample Requests accepted until:	April 28, 2024*	
*Sample requests received after April 28, 2024 will not be supported.					
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of Clark as an additional Assembly site for set of devices listed below. There are no construction differences between the 2 sites.					
Reason for Change:					
Supply continuity					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS		REACH		Green Status	
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change	
IEC 62474					
<input checked="" type="checkbox"/> No Change					
Changes to product identification resulting from this PCN:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
CDAT	CDA	CHN	Chengdu		
Clark	QAB	PHL	Angeles City, Pampanga		
Sample product shipping label (not actual product label)					
Product Affected:					

TPS552882RPMR

TPS55288RPMR

TI Information
Selective Disclosure

Qualification Report

TPS55288xRPMR
Approve Date 27-March-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device:	Qual Device:	Process QBS Reference:	Package/Product QBS Reference:	Package QBS Reference:
					TPS552882RPMR	TPS55288RPMR			
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/45/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0	3/231/0	-
HTOL	B1	Life Test	150C	408 Hours	-	-	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	1/800/0	-

Type	#	Test Name	Condition	Duration	Qual Device:	Qual Device:	Process QBS Reference:	Package/Product QBS Reference:	Package QBS Reference:
					<u>TPS552882RPMR</u>	<u>TPS55288RPMR</u>	<u>TPS61378QWRTERQ1</u>	<u>TPS552882QRPMRQ1</u>	<u>TPS552882QRPMRQ1</u>
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	-	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	3/90/0	3/90/0	3/90/0
FTY	E6	Final Test Yield	-	-	1/All/0	1/All/0	-	-	1/All/0

- QBS: Qual By Similarity
- Qual Device TPS552882RPMR is qualified at MSL2 260C
- Qual Device TPS55288RPMR is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2305-017

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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